

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	25	@ad<="20031022" and 'circuit board' and 'trace' with 'high dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 09:15
L3	1	"4967314".PN.	USPAT; USOCR	OR	ON	2005/04/29 08:17
L4	2	@ad<="20031022" and 'trace' with 'high dielectric' same 'solder'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 09:15
L5	150	@ad<="20031022" and 'PCB' and 'signal trace' and 'mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 09:39
L6	11	@ad<="20031022" and 'PCB' and 'signal trace' with 'mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:18
L7	71	@ad<="20031022" and 'PCB' and 'copper' with 'trace' with 'mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 09:48
L9	0	@ad<="20031022" and 'PCB' and 'copper' with 'trace' with 'mask' and 'high k'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 09:48
L10	4	Han-Dong-Ho.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:18
L12	18	@ad<="20031022" and 'trace' with ('polyvinylidene diflouride' or pvdf)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:09
L13	338	@ad<="20031022" and 'copper' with ('polyvinylidene diflouride' or pvdf)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:17
L14	0	@ad<="20031022" and 'solder mask' same 'copper' with ('polyvinylidene diflouride' or pvdf)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:10

L15	5	@ad<="20031022" and 'PCB' and 'copper' with ('polyvinylidene diflouride' or pvdf)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:17
L16	0	@ad<="20031022" and 'PCB' and 'copper' and 'filler' with ('polyvinylidene diflouride' or pvdf)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:17
L17	153	@ad<="20031022" and 'filler' with ('polyvinylidene diflouride' or pvdf)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:17
L18	0	@ad<="20031022" and 'copper' same 'filler' with ('polyvinylidene diflouride' or pvdf)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:18
S1	722	@ad<="20031022" and 'PCB' and 'signal trace'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 09:17
S2	71	@ad<="20031022" and 'PCB' and 'signal trace' and 'low impedance'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 08:49
S3	140	@ad<="20031022" and 'differential' with 'signal trace'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 10:59
S4	49	@ad<="20031022" and 'PCB' and 'differential' with 'signal trace'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 09:12
S5	1	"6005895".PN.	USPAT; USOCR	OR	ON	2005/01/12 08:59
S6	1	"5956518".PN.	USPAT; USOCR	OR	ON	2005/01/12 09:00
S7	7	@ad<="20031022" and 'copper trace' same 'coupling' same 'dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 09:21
S8	70	@ad<="20031022" and 'copper' with 'high dielectric' same 'low dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 09:42

S9	115	@ad<="20031022" and 'interconnection' and 'copper layer' and 'high dielectric' and 'low dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 09:42
S10	13	@ad<="20031022" and 'differential' with 'signal line' and 'high dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 10:29
S11	735	@ad<="20031022" and (257/664-665).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:17
S12	585	@ad<="20031022" and 'differential signal line'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 10:48
S13	44	@ad<="20031022" and 'differential signal trace'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 10:30
S14	51	@ad<="20031022" and 'differential signal line' same 'coupling'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 10:45
S15	3	@ad<="20031022" and 'differential signal line' same 'dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 10:50
S16	24	@ad<="20031022" and 'PCB' and 'differential signal line'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 10:50
S17	1	'PCB' and 'base layer' and 'ground plane' and 'stripline'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:00
S18	356	'PCB' and 'stripline'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:00
S19	320	'PCB' and 'stripline' and 'signal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:28

S20	1	"6201194".PN.	USPAT; USOCR	OR	ON	2005/01/12 11:03
S21	1	"6175087".PN.	USPAT; USOCR	OR	ON	2005/01/12 11:04
S22	1	"6171946".PN.	USPAT; USOCR	OR	ON	2005/01/12 11:06
S23	1	"6026564".PN.	USPAT; USOCR	OR	ON	2005/01/12 11:07
S24	245	'PCB' and 'stripline' and 'signal' and 'dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:10
S25	20	'PCB' and 'stripline' and 'signal' and 'high dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:10
S26	10	'Electromagnetic coupler circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:29
S27	356	'Electromagnetic coupler'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:31
S28	217	'Electromagnetic coupler' and 'signal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:40
S29	38	'Electromagnetic coupler' and 'signal line'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:43
S30	102	'Electromagnetic' with 'coupling' and 'signal trace'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:58
S31	4915	'Electromagnetic' with 'coupling' and 'dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:02
S32	497	'Electromagnetic' with 'coupling' and ' high dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:03

S33	20	'PCB' and 'Electromagnetic' with 'coupling' and ' high dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:03
S34	1685	@ad<="20031022" and (257/734-736).cccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:07
S35	1483	@ad<="20031022" and (257/700).cccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:07
S36	1105	@ad<="20031022" and (257/750).cccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 13:34
S37	879	@ad<="20031022" and (257/762).cccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:08
S38	648	@ad<="20031022" and (257/211).cccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:08
S39	2	("0691193").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 12:17
S40	2	("6449308").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 13:07
S41	7	((("3615951") or ("6705895")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 13:07
S42	27	@ad<="20031022" and 'PCB' same 'FR4' same 'resin' same 'fiber'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 13:36

S43	96	@ad<="20031022" and 'FR4' with 'resin' with 'fiber'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 13:36
S44	1	"20050087877"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:33
S45	30	@ad<="20031022" and 'PCB' and 'copper' and 'epoxy' with 'fiber' and 'solder mask' and 'filler'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 15:21
S46	1	@ad<="20031022" and 'PCB' and 'copper' and 'epoxy' with 'fiber' and 'solder mask' and 'filler' with 'polyvinylidene'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:42
S47	19	@ad<="20031022" and 'copper' same 'filler' with 'polyvinylidene'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:43
S48	0	@ad<="20031022" and 'copper' same 'filler' with 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:43
S49	0	@ad<="20031022" and 'coper' same 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:44
S50	0	@ad<="20031022" and 'coper' and 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:44
S51	0	@ad<="20031022" and 'PCB' and 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:44
S52	107	@ad<="20031022" and 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:47
S53	21	@ad<="20031022" and 'dielectric' and 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:04

S54	69	@ad<="20031022" and 'FR4' and 'copper' with 'solder mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 15:21
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